

F1977 Datasheet

5 to 3000 MHz

7-Bit, 75 Ω, Digital Step Attenuator

GENERAL DESCRIPTION

This document describes the specification for the F1977 Digital Step Attenuator. The F1977 is part of a family of *Glitch-Free*TM DSAs optimized for the demanding requirements of CATV and Satellite systems. These devices are offered in a compact 5 mm x 5 mm 32 pin QFN package with 75 Ω impedances for ease of integration.

COMPETITIVE ADVANTAGE

Digital step attenuators are used in Receivers and Transmitters to provide gain control. The F1977 is a 7-bit step attenuator optimized for these demanding applications. The silicon design has very low insertion loss, low distortion (+64 dBm IIP3) and pinpoint attenuation accuracy. Most importantly, the F1977 includes IDT's *Glitch-Free*TM technology which results in low overshoot & ringing during MSB transitions.

- ✓ Lowest insertion loss for best SNR
- ✓ Extremely accurate attenuation levels.
- ✓ Ultra low distortion.
- ✓ Glitch-Free[™] technology to protect PA or ADC during transitions between attenuation states.

APPLICATIONS

- CATV Infrastructure
- CATV Set-Top Boxes
- CATV Satellite Modems
- Data Network Equipment
- Fiber Networks

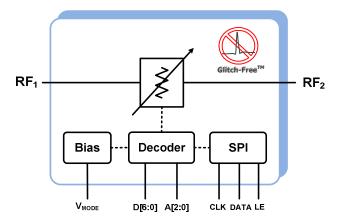
Ordering Information



FEATURES

- Serial & 7 bit Parallel Interface
- 31.75 dB Control Range
- 0.25 dB step
- *Glitch-Free^{†M}* for low transient overshoot
- Low Insertion Loss: 1.4 dB @ 1 GHz
- Ultra linear IIP3: +64 dBm
- Attenuation Error: -0.1 dB @ 1 GHz
- Stable Attenuator Accuracy over temperature
- Bi-directional RF use
- 3.00 V to 5.25 V supply
- 1.8 V or 3.3 V control logic
- Low Current Consumption: 325 µA typical
- -40 °C to +105 °C operating temperature
- 5 mm x 5 mm Thin QFN 32 pin package

FUNCTIONAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Units
V _{DD} to GND	V_{DD}	-0.3	+5.5	V
D[6:0], DATA, CLK, LE, A0, A1, A2, V _{MODE}	V _{CNTL}	-0.3	Minimum (V _{DD} + 0.3, 3.9)	V
DC Voltage RF1, RF2	V_{RF}	-0.3	+0.3	V
Maximum Input Power applied to RF1 or RF2 (>100 MHz)	P_{RF}		+34	dBm
Maximum Junction Temperature	T_{Jmax}		+150	°C
Storage Temperature Range	T _{ST}	-65	+150	°C
Lead Temperature (soldering, 10 s)	T _{LEAD}		+260	°C
Electrostatic Discharge – HBM (JEDEC/ESDA JS-001-2012)	V _{ESDHBM}		1000 (Class 1C)	V
ESD Voltage – CDM (Per JESD22-C101F)	V _{ESDCDM}		500 (Class C2)	V

Stresses above those listed above may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

This product features proprietary protection circuitry. However, it may be damaged if subjected to high energy ESD. Please use proper ESD precautions when handling to avoid damage or loss of performance.

PACKAGE THERMAL AND MOISTURE CHARACTERISTICS

θ_{JA} (Junction – Ambient)	40 °C/W
θ_{JC} (Junction – Case) [The Case is defined as the exposed paddle]	4 °C/W
Moisture Sensitivity Rating (Per J-STD-02	MSL1



Parameter	Symbol	Conditions	Min	Тур	Max	Units
Supply Voltage	V _{DD}		3		5.25	V
Frequency Range	F _{RF}		5		3000	MHz
Operating Temperature Range	T _{CASE}	Exposed Paddle	-40		105	°C
RF CW Input Power	P _{cw}	RF1 or RF2			See Figure 1	dBm
RF1 Impedance	Z _{RF1}	Single Ended		75		Ω
RF2 Impedance	Z _{RF2}	Single Ended		75		Ω

F1977 RECOMMENDED OPERATING CONDITIONS

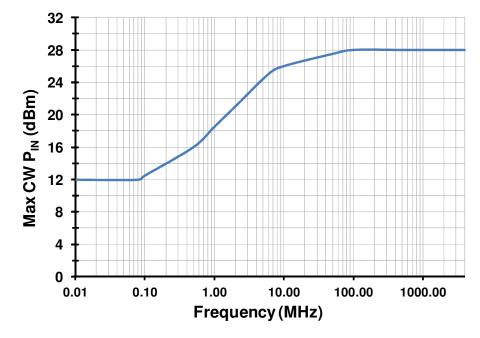


Figure 1 - Maximum Continuous Operating RF input power versus Input Frequency

F1977 SPECIFICATION

Specifications apply at V_{DD} = +3.3 V, T_{CASE} = +25°C, F_{RF} = 1 GHz, Pin = -10 dBm unless otherwise noted. Serial Mode. $Z_{RF1} = Z_{RF2} = 75 \Omega$. EVkit losses are de-embedded unless otherwise noted.

Parameter	Symbol	Conditions	Min	Тур	Max	Units
		CLK, LE, DATA, D[6:0], A0, A1, A2, V _{MODE}				
Logic Input High	V_{IH}	V _{DD} > 3.6 V	1.17 ¹		3.6	v
		$3.0 \le V_{DD} \le 3.6$	1.17		V_{DD}	v
Logic Input Low	V _{IL}	CLK, LE, DATA, D[6:0], A0, A1, A2, V _{MODE}			0.63	V
Logic Current	$I_{IH,} I_{IL}$	Individual Pins	-40		+40	μA
Supply Current	т	V _{DD} = 3.3 V		322	365	
Supply Current	I_{DD}	$V_{DD} = 5.0 V$		375		μA
Attenuation Range	ATT _{RNG}			31.75		dB
Minimum Gain Step	LSB	Monotonic for $F_{RF} \leq 3 \text{ GHz}$		0.25		dB
Incortion Loss	TI	$F_{RF} = 1 \text{ GHz}$		1.4	1.9	٩D
Insertion Loss	IL	$F_{RF} = 2 \text{ GHz to } 3 \text{ GHz}$		2.2		dB
Relative Insertion Phase	•	$F_{RF} = 1 \text{ GHz}$		18		dog
(A _{min} vs. A _{max})	Φ_{Δ}	$F_{RF} = 2 \text{ GHz}$		36		deg
Step Error (Differential Non-Linearity)	DNL	Max error between adjacent steps		0.10		dB
Absolute Attenuation Error	INL	Max Error for state 19.75 dB, $F_{RF} = 1 \text{ GHz}$	-0.4	0.1	+0.5	dP
(Integral Non-Linearity)	INL	Max Error, over all states $F_{RF} = 1 \text{ GHz}$	-0.8		+0.5	– dB
Tana di Dahara di sas	C11	$5 \text{ MHz} \le F_{RF} \le 1.5 \text{ GHz}$		18		-ID
Input Return Loss	S11	$1.5 \text{ GHz} < F_{\text{RF}} \le 3.0 \text{ GHz}$		15		dB
	C22	5 MHz \leq F _{RF} \leq 1.5 GHz		17		م ا
Output Return Loss	S22	$1.5 \text{ GHz} < F_{\text{RF}} \le 3.0 \text{ GHz}$		15		dB

Specification Notes:

Note 1: Items in min/max columns in *bold italics* are Guaranteed by Test.

Note 2: Items in min/max columns that are not bold/italics are Guaranteed by Design Characterization.

Note 3. The input 0.1dB compression point is used as a linearity figure of merit. The recommended maximum input power is specified as the lesser of the two values from Figure 1 and Figure 2 above.

Note 4: Spurious due to on-chip negative voltage generator. Typical generator fundamental frequency is 2.2 MHz.

Note 5: Minimum time required between switching of attenuations states = 1 / (Maximum Switching Rate).

RENESAS

F1977 SPECIFICATION

Specifications apply at V_{DD} = +3.3 V, T_{CASE} = +25°C, F_{RF} = 1 GHz, Pin = -10 dBm unless otherwise noted. Serial Mode. $Z_{RF1} = Z_{RF2} = 75 \Omega$. EVkit losses are de-embedded unless otherwise noted.

Parameter	Symbol	Conditions	Min	Тур	Max	Units	
		$P_{IN} = +10 \text{ dBm per tone}$ 50 MHz Tone Separation					
Input IP3	IIP3	Attn State = 0.00 dB		64			
		Attn State = 15.75 dB		64		dBm	
		Attn State = 31.75 dB		64			
Input 0.1dB Compression ³	P _{0.1dB}	$F_{RF} = 1 \text{ GHz}$ Attn = 10 dB Measured in 50 ohms		32		dBm	
DCA Cottling Time		Max to Min Attenuation to settle to within 0.5 dB of final value		0.9			
DSA Settling Time	τ _{set}	Min to Max Attenuation to settle to within 0.5 dB of final value		1.8		— μs	
Video Feedthrough RF1, RF2 ports	VID _{FT}	Measured at RF ports with 2.5 ns risetime, 0 to 3.3 V control pulse		10		mV _{pp}	
Maximum spurious level on any RF port ⁴	Spur _{MAX}	Spur Freq ~ 2.2 MHz		-119		dBm	
Serial Clock Speed	F _{CLK}	SPI 3 wire bus			25	MHz	
Parallel to Serial Setup	А	SPI 3 wire bus	100			ns	
Serial Data Hold Time	В	SPI 3 wire bus	10			ns	
LE Delay	С	SPI 3 wire bus Time from final serial clock rising edge	10			ns	
Maximum Switching Rate ⁵	SW _{RATE}			25		kHz	

Specification Notes:

Note 1: Items in min/max columns in *bold italics* are Guaranteed by Test.

Note 2: Items in min/max columns that are not bold/italics are Guaranteed by Design Characterization.

Note 3. The input 0.1dB compression point is used as a linearity figure of merit. The recommended maximum input power is specified as the lesser of the two values from Figure 1 and Figure 2 above.

Note 4: Spurious due to on-chip negative voltage generator. Typical generator fundamental frequency is 2.2 MHz.

Note 5: Minimum time required between switching of attenuations states = 1 / (Maximum Switching Rate).

RENESAS

PROGRAMMING OPTIONS

F1977 can be programmed using either the parallel or serial interface; selectable via V_{MODE} (pin 3). Serial mode is selected by floating V_{MODE} or pulling V_{MODE} to a logic high and parallel mode is selected by setting V_{MODE} to logic low.

SERIAL CONTROL MODE

F1977 Serial mode is selected by floating V_{MODE} (pin 3) or pulling it to logic high. The serial interface is a 16-bit shift register made up of two words. The first 8-bit word is the Attenuation word, which controls the DSA state. The second word is the address word, which uses only 3 of 8-bits that must match the hard wired A0-A2 programming in order to change the DSA state. If no external connections are made to A0 – A2 then internally they will default to 000 due to internal pull down resistors. If these 3 external preset address bits are not matched with the SPI loaded address bits then the current attenuator state will remain unchanged. This allows up to 8 serial-controlled devices to be used on a single board, which share a common DATA, CLK and LE.

When serial programming is used, all the parallel control input pins 26 - 32 can be left open or grounded. If a pin is grounded than an additional $25 \ \mu$ A will be drawn from the voltage supply per pin.

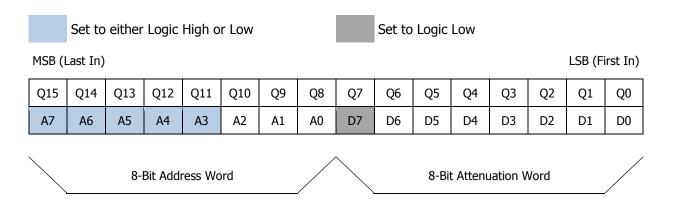


Figure 2 - Two 8-bit words are comprised of 16-bit serial in, parallel out shift register

A7 (MSB)	A6	A5	A4	А3	A2	A1	AO	Address Setting
Х	Х	Х	Х	Х	0	0	0	000
Х	Х	Х	Х	Х	0	0	1	001
Х	Х	Х	Х	Х	0	1	0	010
Х	Х	Х	Х	Х	0	1	1	011
Х	Х	Х	Х	Х	1	0	0	100
Х	Х	Х	Х	Х	1	0	1	101
Х	Х	Х	Х	Х	1	1	0	110
Х	Х	Х	Х	Х	1	1	1	111

Table 1 - Truth Table for the Serial Address Word

D7	D6	D5	D4	D3	D2	D1	D0 (LSB)	Attenuation State (dB)
0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	1	0.25
0	0	0	0	0	0	1	0	0.5
0	0	0	0	0	1	0	0	1
0	0	0	0	1	0	0	0	2
0	0	0	1	0	0	0	0	4
0	0	1	0	0	0	0	0	8
0	1	0	0	0	0	0	0	16
0	1	1	1	1	1	1	1	31.75

SERIAL MODE DEFAULT CONDITION

When the device is first powered up it will default to the **Maximum Attenuation** setting as described below: Note that for the F1977 in all cases logic high (1) = Attenuation Stepped IN, while logic Low (0) = Attenuation Stepped OUT.

MSB (Last In)

LSB (First In)

Q	215	Q14	Q13	Q12	Q11	Q10	Q9	Q8	Q7	Q6	Q5	Q4	Q3	Q2	Q1	Q0
A	47	A6	A5	A4	A3	A2	A1	A0	D7	D6	D5	D4	D3	D2	D1	D0
	Х	Х	Х	Х	Х	0	0	0	0	1	1	1	1	1	1	1
			8-	Bit Addı	ress Wo	ord					8-Bit	t Attenı	iation V	Vord		

Figure 3 -Default register settings set for Max Attenuation and 000 Address Word

REGISTER TIMING DIAGRAM: (NOTE THE TIMING SPEC INTERVALS IN BLUE)

With serial control, the F1977 can be programmed via the serial port on the rising edge of Latch Enable (LE) which loads the last 8 DATA line bits [formatted LSB (D0) first] resident in the SHIFT register followed by the Address Word into the ACTIVE register.

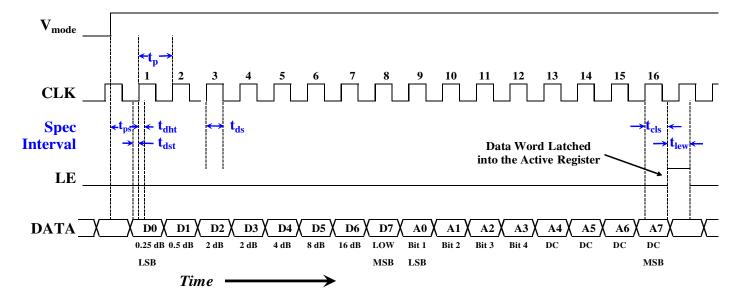


Figure 4 - Serial Timing Diagram

Note - When Latch Enable (LE) is high, the shift register is disabled and DATA is NOT continuously clocked into the shift register which minimizes noise. It is recommended that Latch enable be left high when the device is not being programmed.

Interval Symbol	Description	Min Spec	Max Spec	Units
t _{ps}	Parallel to Serial Setup Time - From rising edge of Vmode to rising edge of CLK for D5	100		ns
tp	Clock high pulse width	10		ns
t _{cls}	LE Setup Time - From the rising edge of CLK pulse for D0 to LE rising edge minus half the clock period.	10		ns
t _{lew}	LE pulse width	30		ns
t _{dst}	Data Setup Time - From the starting edge of Data bit to rising edge of CLK	10		ns
t _{dht}	Data Hold Time - From rising edge of CLK to falling edge of the Data bit.	10		ns

Table 3 ·	- Serial	Mode	Timing	Table
-----------	----------	------	--------	-------

PARALLEL CONTROL MODE

For the F1977 the user has the option of running in one of two parallel modes. Direct Parallel Mode or Latched Parallel Mode.

Direct Parallel Mode:

Direct Parallel Mode is selected when V_{MODE} is a logic low and LE is a logic high. In this mode the device will immediately react to any voltage changes to the parallel control pins [pins 26 – 32]. Use direct parallel mode for the fastest settling time.



Latched Parallel Mode:

Latched Parallel Mode is selected when V_{MODE} is logic low and LE is toggled from logic low to high. To utilize Latched Parallel Mode:

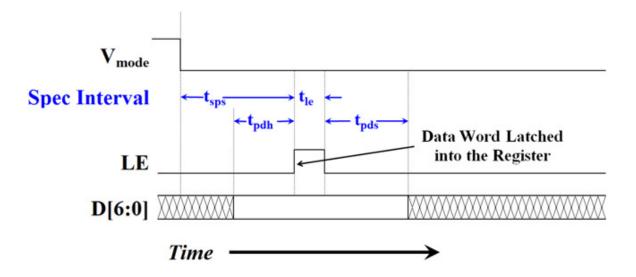
- Set V_{MODE} is logic low.
- Set LE to logic low.
- Adjust pins [26, 27, 28, 29, 30, 31, 32] to the desired attenuation setting. (While LE is set to a logic low, the attenuation state will not change.)
- Pull LE to a logic high. The device will then transition to the attenuation settings reflected by pins D6 D0.

Latched Parallel Default Startup Condition:

Latched Parallel Mode implies a default state for when the device is first powered up with V_{MODE} set for logic low and LE logic low. In this case the default setting is MAXIMUM Attenuation.

D6	D5	D4	D3	D2	D1	D0	Attenuation (dB)			
0	0	0	0	0	0	0	0			
0	0	0	0	0	0	1	0.25			
0	0	0	0	0	1	0	0.5			
0	0	0	0	1	0	0	1			
0	0	0	1	0	0	0	2			
0	0	1	0	0	0	0	4			
0	1	0	0	0	0	0	8			
1	0	0	0	0	0	0	16			
1	1	1	1	1	1	1	31.75			

 Table 4 - Truth Table for the Parallel Control Word





Interval Symbol	Description		Max Spec	Units
t _{sps}	Serial to Parallel Mode Setup Time	100		ns
t _{pdh}	Parallel Data Hold Time	10		ns
t _{le}	t _{le} LE minimum pulse width			ns
t _{pds}	Parallel Data Setup Time	10		ns

Table 5 - Latched Parallel Mode Timing

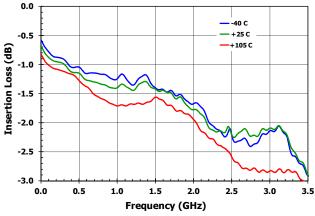
TYPICAL OPERATING CONDITIONS (TOC)

Unless otherwise noted for the TOC graphs on the following pages, the following conditions apply.

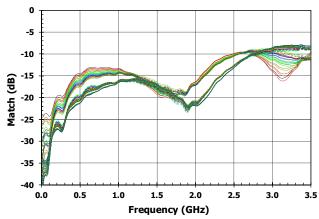
- V_{DD} = +3.30 V
- T_{CASE} = +25 °C
- P_{IN} = 0 dBm for single tone measurements
- P_{IN} = +15 dBm/tone for multi-tone measurements
- 50 MHz Tone Space
- Serial Control
- RF1 Port is the input port
- Attenuation Setting = 0 dB
- Measured in a 75 ohm system
- EVKit losses (traces and connectors) are fully de-embedded

TYPICAL OPERATING CONDITIONS (-1-)

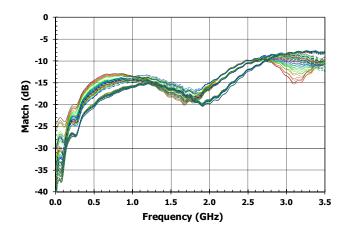
Insertion Loss vs Frequency



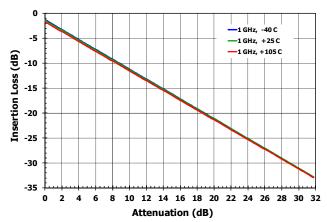
RF1 Return Loss vs Frequency [All States]



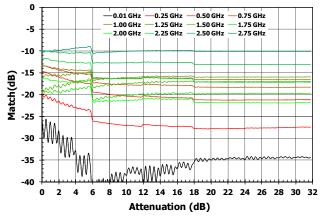
RF2 Return Loss vs Frequency [All States]



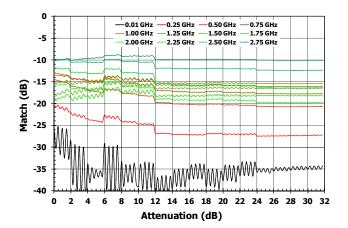
Insertion Loss vs Attenuation State



RF1 Return Loss vs Attenuation State

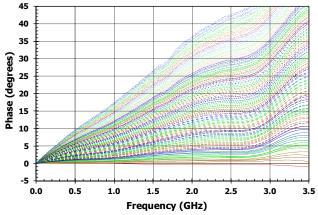


RF2 Return Loss vs Attenuation State

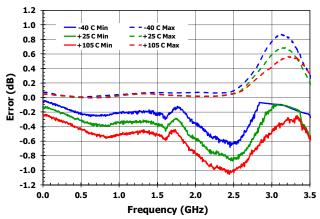


TYPICAL OPERATING CONDITIONS (-2-)

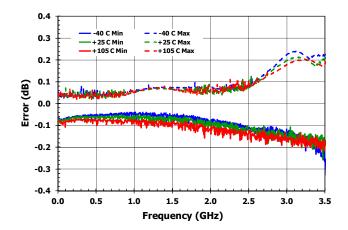
Relative Insertion Phase vs Frequency



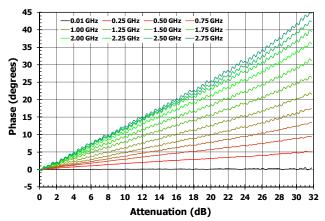
Worst Case Absolute Accuracy vs Frequency



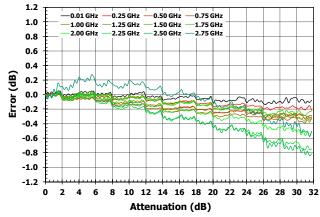
Worst Case Step Accuracy vs Frequency

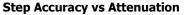


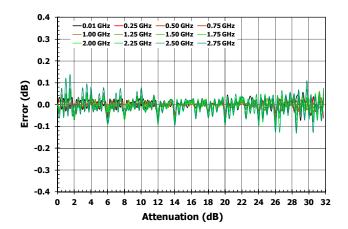
Relative Insertion Phase vs Attenuation



Absolute Accuracy vs Attenuation





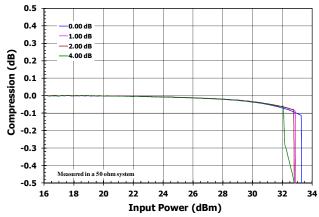


Input Compression at 50 MHz

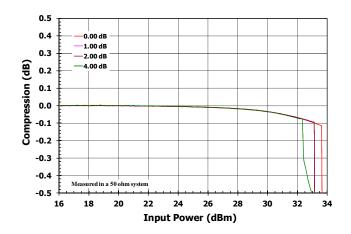
TYPICAL OPERATING CONDITIONS (-3-)

0.5 0.4 0.00 dB -1.00 dB 0.3 -2.00 dB 4.00 dB Compression (dB) 0.2 0.1 0.0 -0.1 -0.2 -0.3 -0.4 l in a 50 -0.5 16 18 20 22 24 26 28 30 32 34 Input Power (dBm)

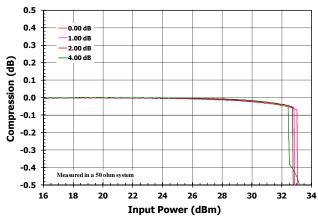
Input Compression 1.0 GHz



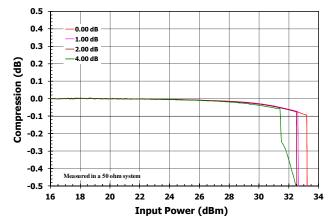
Input Compression 2.0 GHz



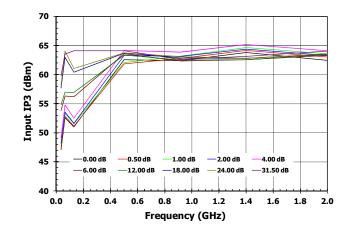
Input Compression 500 MHz



Input Compression 1.5 GHz



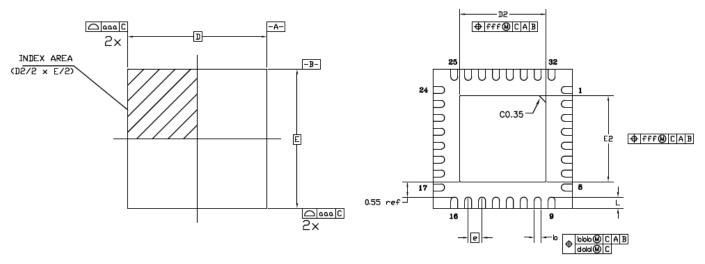






PACKAGE DRAWING

(5 mm x 5 mm 32-pin TQFN), Use Exposed PAD (EPAD) Option P1



TOP VIEW

BOTTOM VIEW

SIDE VIEW

A1

SEAT ING

-C-

SYMBOL	DIMENSION			
2	MIN	NOM	MAX	
L	0.30	0.40	0.50	
D	5	.00 BSC		
E	5.00 BSC			
е	0.50 BSC			
А	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
b	.20	.25	.30	
aaa	0.10			
bbb	0.10			
CCC	0.10			
ddd	0.05			
eee	0.08			
fff	0.10			

FPAD	OPTION	

⊂ eee C

// ccc C

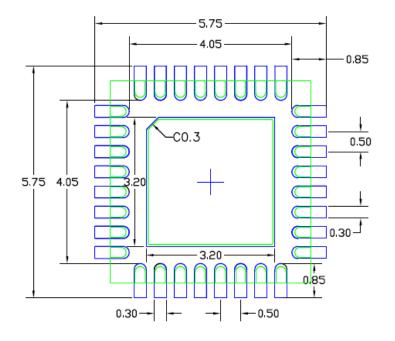
SYMBOL	P1			
STMDUL	MIN	NOM	MAX	
E2	3.00	3.10	3.20	
D2	3.00	3.10	3.20	

NOTES:

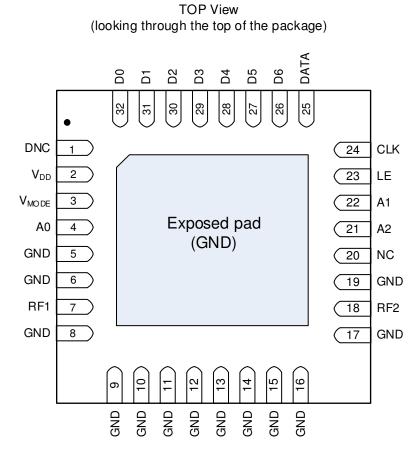
1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982 2. ALL DIMENSIONS ARE IN MILLIMETERS.



LAND PATTERN DIMENSION



PIN DIAGRAM



Rev 1, 04/21/2016



PIN DESCRIPTION

Pin	Pin Name Function		
1	DNC	This pin must be left open.	
2	V _{DD}	Main Supply. Use 3.3 V or 5 V. Bypass capacitor as close to pin as possible.	
3	V _{MODE} ¹	Logic low for parallel mode. Logic high or NC for serial mode.	
4	A0 ²	Address bit A0 connection.	
5	GND	Connect directly to paddle ground or as close as possible to pin with thru via. This pin is not internally connected.	
6	GND	Connect directly to paddle ground or as close as possible to pin with thru via.	
7	RF1 ³	Device RF input or output (bi-directional).	
8 - 17	GND	Connect each pin directly to paddle ground or as close as possible to pin with thru vias.	
18	RF2 ³	Device RF input or output (bi-directional).	
19	GND	Connect directly to paddle ground or as close as possible to pin with thru via.	
20	NC	No internal connection. These pins can be left unconnected, voltage applied, or connected to ground (recommended).	
21	A2 ²	Address bit A2 connection	
22	A1 ²	Address bit A1 connection.	
23	LE1	Serial interface latch enable input.	
24	CLK ¹	Serial interface clock input.	
25	DATA ¹	Serial interface data input.	
26	D6 ¹	Parallel control bit, 16 dB.	
27	D5 ¹	Parallel control bit, 8 dB.	
28	$D4^1$	Parallel control bit, 4 dB.	
29	D3 ¹	Parallel control bit, 2 dB.	
30	D2 ¹	Parallel control bit, 1 dB.	
31	D1 ¹	Parallel control bit, 0.5 dB.	
32	D0 ¹	Parallel control bit, 0.25 dB.	
EP	Exposed Paddle	Connect to Ground with multiple vias for good thermal and RF performance.	

Pin Description Notes:

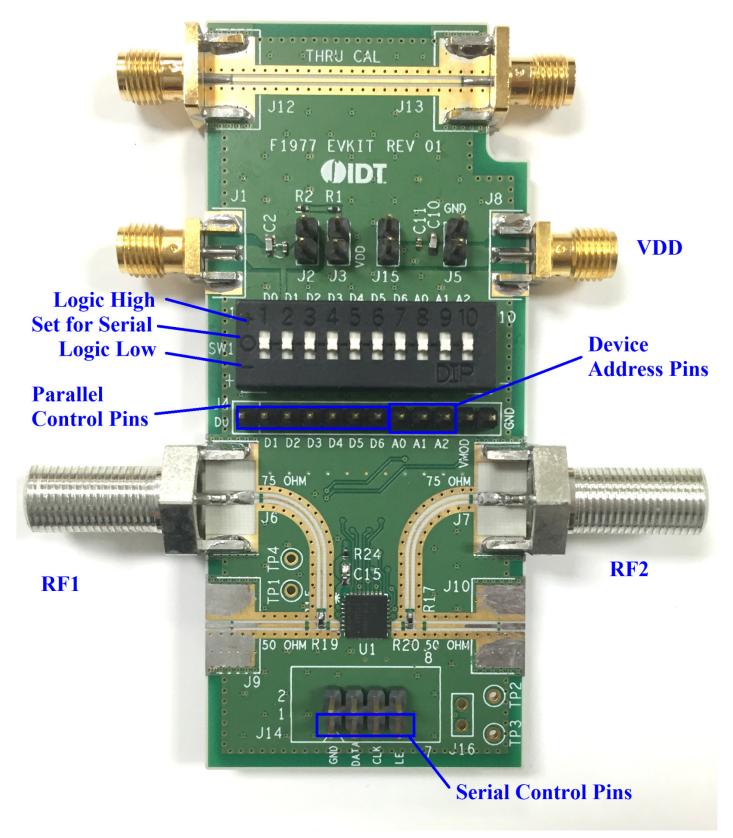
Note 1: Includes an internal 100 kΩ pullup resistor to an internal regulated 2.5V supply. If pin is grounded then there is an additional 25 µA per pin for the supply current. Includes an internal 100 k Ω pull-down resistor to GND.

Note 2:

Note 3: RF pins 7 and 18 do not require DC blocking capacitors for operation if they are at 0 V DC. If they are not at 0V DC, then they require DC blocking capacitors.

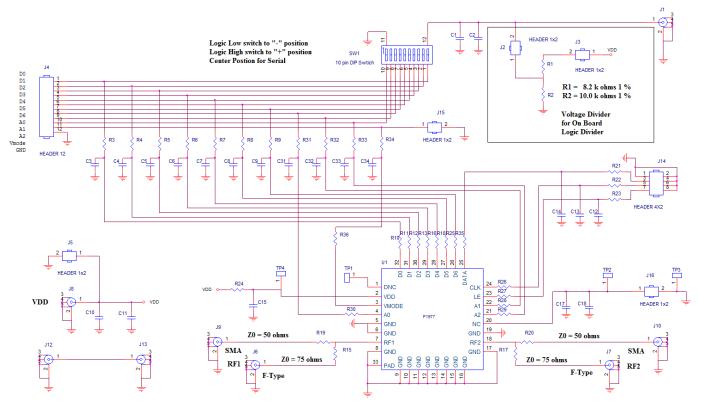


EVKIT PICTURE





EVKIT / APPLICATIONS CIRCUIT

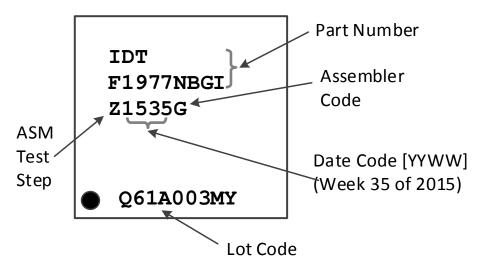




EVKIT BOM

Item #	Part Reference	QTY	DESCRIPTION	Mfr. Part #	Mfr.
1	C1, C11, C15	3	100 nF ±10%, 16 V, X7R Ceramic Capacitor (0402)	GRM155R71C104K	MURATA
2	C2, C10	2	10 nF ±5%, 50 V, X7R Ceramic Capacitor (0603)	GRM188R71H103J	MURATA
3	C3 - C9, C12, C13, C14, C31 - C34	14	100 pF ±5%, 50 V, C0G Ceramic Capacitor (0402)	GRM1555C1H101J	MURATA
4	R3 - R9, R31 - R34	11	100 Ω ±1%, 1/10W, Resistor (0402)	ERJ-2RKF1000X	PANASONIC
5	R10-R13, R15-R18, R24-R30, R35, R36	17	0 Ω Resistors (0402)	ERJ-2GE0R00X	PANASONIC
6	R21, R22, R23	3	3 kΩ ±1%, 1/10W, Resistor (0402)	ERJ-2RKF3001X	PANASONIC
7	R1	1	8.2 kΩ ±1%, 1/10W, Resistor (0402)	ERJ-2RKF8201X	PANASONIC
8	R2	1	10 kΩ ±1%, 1/10W, Resistor (0402)	ERJ-2RKF1002X	PANASONIC
9	J2, J3, J5	3	CONN HEADER VERT SGL 2 X 1 POS GOLD	961102-6404-AR	3M
10	J14, J15	1	CONN HEADER VERT DBL 4 X 2 POS GOLD	67997-108HLF	FCI
11]4	1	CONN HEADER VERT SGL 12 X 1 POS GOLD	961112-6404-AR	3M
12	J1, J8	2	Edge Launch SMA (0.250 inch pitch ground, round)	142-0711-821	Emerson Johnson
13	J6, J7	2	Edge Launch F TYPE 75 ohm SMA	222181	Amphenol
14	U2	1	SWITCH 10 POSITION DIP SWITCH	KAT1110E	E-Switch
15	U1	1	DSA	F1977NCGI	IDT
16		1	Printed Circuit Board	F1977 Evkit Rev 01	IDT

TOP MARKINGS





APPLICATIONS INFORMATION

Power Supplies

A common VCC power supply should be used for all pins requiring DC power. All supply pins should be bypassed with external capacitors to minimize noise and fast transients. Supply noise can degrade noise figure and fast transients can trigger ESD clamps and cause them to fail. Supply voltage change or transients should have a slew rate smaller than 1 V / 20 μ S. In addition, all control pins should remain at 0 V (+/-0.3 V) while the supply voltage ramps or while it returns to zero.

Digital Pin Voltage & Resistance Values

The following table provides open-circuit DC voltage referenced to ground and resistance values for each of the control pins listed.

Pin	Name	Open Circuit DC Voltage	Internal Connection
3	V _{MODE}	2.5 V	100 k Ω pullup resistor to internally regulated 2.5 V
4, 21, 22	A0, A2, A1	0 V	100 k Ω resistor to GND
23, 24, 25	LE, CLK, DATA	2.5 V	100 k Ω pullup resistor to internally regulated 2.5 V
26-32	D[6:0]	2.5 V	100 k Ω pullup resistor to internally regulated 2.5 V



REVISION HISTORY SHEET

Rev	Date	Page	Description of Change
0	2016-Feb-19		Initial Release
1	2016-Apr-21	2	Typo on V_{HBM} rating. Voltage changed from 1.5kV to 1kV. No chng. to Class